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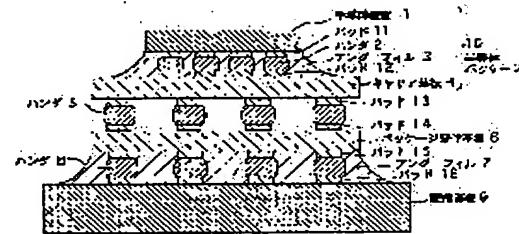
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(54) MOUNTING STRUCTURE FOR SEMICONDUCTOR DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a mounting structure of the semiconductor device for mounting a semiconductor package with pair chips mounted thereon, and a large number of external thermals onto a printed circuit board through solder bump connections.

SOLUTION: In the structure of mounting a semiconductor package 10 onto a printed circuit board 9, a package-receiving board 6 whose outer size is nearly the same as or larger than the semiconductor package 10, having a pad 14 to be connected to the semiconductor package 10 on its upper face, and having a pad 15 to connect to a wiring board 9 at its lower side, is placed at a semiconductor conductor package-mounting position on the wiring board 9, the pad 16 of the wiring board 9 and the pad 15 at the lower face of the package-receiving board 6 are soldered by solder 8 and an under fill 7 is filled and fixed at the soldering part.



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